

Title (en)
ELECTRONIC COMPONENT

Title (de)
ELEKTRONISCHES BAUELEMENT

Title (fr)
COMPOSANT ELECTRONIQUE

Publication
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Application
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Abstract (en)
[origin: DE19818824A1] The invention relates to a surface wave component and to a method for the production of the same, comprising a chip (2) with a piezoelectric substrate, electronic conductive structures arranged on said chip (IDT converters, contact strips and the like), a base plate (3) with external contact elements contacting the electric conductive structures of the chip and a hermetically sealed frame (4) mounted on the base plate, the chip being arranged inside and at a distance from said frame. The area between the chip (2) and the base plate (3) is sealed off with a foil (5), the area between the frame (4) and the foil (5) is filled with a sealing compound (6) and the chip (2) along with the sealing compound (6) and the frame (4) are protected by a cover (7) or a protective cap made of galvanic material, the edges (8) of which rest on the base plate (3) hermetically sealing the latter.

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IPC 8 full level
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